

Docket No.: 24061.48 / 2003-0059  
Customer No.: 42717

THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant:	Chuan-Jen Wu, et al.	§	Docket No.:	24061.48 / 2003-0059
Serial No.:	10/823,867	§	Examiner:	TBD
Filing Date:	April 14, 2004	§	Art Unit:	2121
Entitled:	Job Flow Petri Net and Controlling Mechanism for Parallel Processing	§	Conf. No:	6172

PETITION FOR FILING ON BEHALF OF NONSIGNING INVENTOR  
PURSUANT TO 37 C.F.R. § 1.47(a)

Commissioner for Patents  
Mail Stop: Missing Parts  
P.O. Box 1450  
Alexandria, VA 22313-1450

Dear Sir:

In response to the Notice to File Missing Parts of Nonprovisional Application mailed on June 24, 2004 for the above-identified application, the undersigned attorney for applicant hereby provides the following pertinent facts, in accordance with 37 C.F.R. § 1.47(a):

1. At the time of filing the application, all of the named inventors were full-time employees with Taiwan Semiconductor Manufacturing Company, Ltd ("TSMC"). Inventors, Chuan-Jen Wu and Tien-Hsiang Sun, have since left TSMC.
2. On April 14, 2004, a letter was sent to TSMC enclosing a Declaration and Assignment to obtain signatures from all of the named inventors.
3. Monthly reminder emails since April 2004 were sent to TSMC requesting the return of an executed Declaration and Assignment
4. Applicants enclose herewith a copy of correspondence dated January 17, 2005 transmitting the application papers (specification, including claims, drawings and declaration) to Chuan-Jen Wu and Tien-Hsiang Sun. Also, enclosed is a copy of the mail certificate showing the cover letter and enclosures were sent via registered mail nos. 134165 and 134166.
5. Accordingly, Applicants submit that after a diligent effort, the inventors, Chuan-Jen Wu and Tien-Hsiang Sun, refuses to sign or cannot be reached.
6. Chuan-Jan Wu's last known address is 72 Jhunguang Rd., Hsin-Chu, Taiwan 300, R.O.C.
7. Tien-Hsiang Sun's last known address is 1F, No. 21, Alley 16, Lane 199, Dunhua N. Rd., Taipei, Taiwan 105, R.O.C.

01/31/2005 BABRAHA1 00000003 10823867-

02-FC:1464

Adjustment date: 02/03/2005 BABRAHA1-

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02/03/2005 BABRAHA1 00000042 081394 10823867

01 FC:1463 70.00 DA 130.00 OP

-130.00-OP

-130.00-OP

8. Applicants further submit that application be made by the signing inventor, Chyuarn-Yuh Dai, on behalf of himself and on behalf of the nonsigning inventors.
9. A check for the fee payment totaling \$2420.00 (\$130.00 Surcharge for Missing Parts, \$2,160.00 for Petition for Five-Month Extension Fee and \$130.00 for Petition for Filing on Behalf of Nonsigning Inventor).

For the reasons set forth above, Applicants respectfully request that this Petition be granted and that the application be allowed to proceed with examination.

Respectfully submitted,



David M. O'Dell  
Reg. No. 42,044

Date: 1-24-05

HAYNES AND BOONE, LLP  
901 Main Street, Suite 3100  
Dallas, Texas 75202-3789  
Telephone: 972-739-8638  
IP Facsimile: 214-200-0853

**CERTIFICATE OF MAILING**

I hereby certify that this correspondence is being deposited with the U.S. Postal Service as First Class Mail in an envelope addressed to Commissioner for Patents, Mail Stop: Missing Parts, P.O. Box 1450, Alexandria, VA 22313-1450 on the date indicated below.

Bonnie Boyle  
Name

1-24-05  
Date

收寄局編 (已收寄局編)

中華民國 94 年 1 月 17 日

寄件人名稱: 李永祥

寄件人代表

台灣積體電路製造股份有限公司

台南741科學工業區南科北路1號

郵政特准掛號 5052000 特准掛號 5052058

詳細地址:

電話號碼:

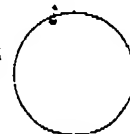
順序號碼	掛號號碼	收件人姓名	寄遞地名(或地址)	重量	郵資	備註
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2	34/66	孫永相	105			44:
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李永祥

- 約定事項**
- (1)此單請寫一式二份。
  - (2)限時掛號、掛號郵件與快捷郵件不得同列一單，請將標題塗去其二。
  - (3)郵件背面應註明掛號號碼，並按號碼次序排列，滿二十件為一組分別交寄。
  - (4)將本單與外埠郵件分別列單交寄。
  - (5)郵件應妥為包裝，如裝小包或快捷郵件，內裝易脆物品者，請於封套正面加貼「脆弱郵件」貼紙，並請小心搬運，紅杯標頭。
  - (6)如有證明郵件、裝妥必妥者，應由寄件人自行在封套背面內分別註明，並貼填郵票，交郵局處理，如未註明，郵局將按普通郵件處理。
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  - (8)掛號郵件補償金額每件最多不逾新台幣伍佰柒拾伍元。
  - (9)錢鈔或有價證券請利用保價或保價交寄。
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台灣積體電路製造股份有限公司

Taiwan Semiconductor Manufacturing Company, Ltd.

741-44台南科學工業園區南科北路1號

1, Nan-Ke North Rd., Tainan Science Park, Tainan, Taiwan 741-44, R.O.C.

Tel: 886-6-5059688 Fax: 886-6-5052057 Tie-Line: 886-3-5636688

Dear Chuan-Jen, Wu

Enclosed for your review is a copy of the specification for tsmc2003-0059, including claims and drawings, for the referenced application.

Once you have reviewed the application (tsmc2003-0059), please execute the enclosed Declaration and Assignment. Please return the executed Declaration and Assignment to me as soon as possible for filing with the U.S. Patent and Trademark Office.

Should you have any questions or need anything further, please contact with me (Joy Tel:06-5098010). Thanks!

With Best Regards,

Joy Cho Jan. 17, 2005

Joy Cho

Best Available Copy



## 台灣積體電路製造股份有限公司

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1, Nan-Ke North Rd., Tainan Science Park, Tainan, Taiwan 741-44, R.O.C.

Tel: 886-6-5059688 Fax: 886-6-5052057 Tie-Line: 886-3-5636688

Dear Tien-Hsiang, Sun

Enclosed for your review is a copy of the specification for tsmc2003-0059, including claims and drawings, for the referenced application.

Once you have reviewed the application (tsmc2003-0059), please execute the enclosed Declaration and Assignment. Please return the executed Declaration and Assignment to me as soon as possible for filing with the U.S. Patent and Trademark Office.

Should you have any questions or need anything further, please contact with me (Joy Tel:06-5098010). Thanks!

With Best Regards,

*Joy Chou* Jan 17, 2005  
Joy Chou